

TEMPERATURE-CONTROLLED THERMAL PLATFORM FOR AUTOMATED TESTING

Abstract of the Disclosure

5 A temperature-controlled system and method for supporting a wafer or packaged
integrated circuit (IC) under test are described. The system includes a thermal platform
having a top surface assembly on which the wafer or IC can be mounted. A thermal plate is
located under and in thermal communication with the top surface assembly. The thermal
plate is made of a porous thermally conductive material. A temperature-controlled fluid
such as air enters and propagates radially through the porous material of the thermal plate.
10 The temperature of the wafer or IC is controlled by controlling the temperature of the air
passing through the thermal plate. The plate can be made of a sintered metal such as
copper or a reticulated foam or a carbon or graphite foam.

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